CLAIMS

[Claim 1] A cleaning composition for stripping a resin mask, comprising:

a polyhydric alcohol (component A);

amines (component B); and

an organic solvent (component C) with a Hansen solubility parameter, SP value, of 18 to 33 $MPa^{1/2}$, excluding the component A and the component B,

wherein a mass ratio A/B of the component A to the component B is 2 or more and 8 or less,

a mass ratio C/B of the component C to the component B is 15 or more and 100 or less, and

the component C is at least one selected from the group consisting of a sulfur-containing compound and a nitrogen-containing compound.

[Claim 2] The cleaning composition according to claim 1, wherein the component A is at least one selected from the group consisting of ethylene glycol and diethylene glycol.

[Claim 3] The cleaning composition according to claim 1 or 2, wherein the component B is an alkanolamine.

[Claim 4] The cleaning composition according to any one of claims 1 to 3, wherein the component C is a mixed organic solvent consisting of a sulfur-containing compound and a nitrogen-containing compound.

[Claim 5] The cleaning composition according to any one of claims 1 to 4, wherein a content of the component A is 4% by mass or more and 16% by mass or less.

[Claim 6] The cleaning composition according to any one of claims 1 to 5, wherein a content of the component B is 0.5% by mass or more and 8% by mass or less.

[Claim 7] The cleaning composition according to any one of claims 1 to 6, wherein a total content of the component A and the component C is 90% by mass or more and 99.5% by mass or less.

[Claim 8] The cleaning composition according to any one of claims 1 to 7, further comprising saccharides (component D),

wherein a content of the component D is 0.01% by mass or more and 3% by mass or less.

[Claim 9] The cleaning composition according to claim 8, wherein a molecular weight of the component D is 35 or more and 700 or less.

[Claim 10] The cleaning composition according to any one of claims 1 to 9, wherein a content of water (component E) is 3% by mass or less.

[Claim 11] A cleaning method comprising:

stripping a resin mask from an object to be cleaned, to which the resin mask is attached, by using a cleaning composition,

the cleaning composition comprising a polyhydric alcohol (component A), amines (component B), and an organic solvent (component C) with a Hansen solubility parameter, SP value, of 18 to 33 $MPa^{1/2}$, excluding the component A and the component B,

wherein a mass ratio A/B of the component A to the component B is 2 or more and 8 or less,

a mass ratio C/B of the component C to the component B is 15 or more and 100 or less, and

the component C is at least one selected from the group consisting of a sulfur-containing compound and a nitrogen-containing compound.

[Claim 12] A method for producing a semiconductor device, comprising:

stripping a resin mask from an object to be cleaned, to which the resin mask is attached, by using the cleaning composition according to any one of claims 1 to 10.

[Claim 13] A method for producing a semiconductor device, comprising:

stripping a resin mask from an object to be cleaned, to which the resin mask is attached, by using the cleaning method according to claim 11.